

Miniature Rotary Switch SB16, SBI16





Miniature switch for free wiring or direct soldering. According to DIN 41633 and IEC-draft.

- Suitable for MIL-S-3786C and VG 95318, explosion proof according to MIL-STD810C, method 511, Test procedure I.
- •17 mm diameter.
- Special design available for "dry circuits".
- Dust-proof and flux-proof.

SBI16

• Version with additional impulse contact, e.g. for testing or paging functions.

1.0 Construction					
1.1 Number of wafers max.	1 wafer				
1.2 Switching combinations per wafer Design E, detent angle 30°	1x12 to 1x2; 2x6 to 2x2 3x4 to 3x2; 4x3 to 4x2; 6x2				
1.3 Contacts	Soldering lugs or pins				
1.4 Mounting	Central mounting				

2.0	Electrical Data		Ag-version	Au-version
2.1	Switching power max.		10 VA/W	5VA/W
2.2	.2 Switching voltage max.		125 V~/150 V-	60 V≃
_	Switching voltage max. impulse contact		30 V~	30 V~
2.3	Switching current max.		350 mA	100 mA
2.4	Rest current max. at ∂u	u 20°C	≤5A	≤2A
2.5	.5 Test voltage at 50 Hz		1000 V~	1000 V~
	Test voltage impulse contact		500 V~	500 V~
2.6	Life expectancy	without power	≥50 000 cycles	≥ 20 000 cycles
		with power max.	≥20 000 cycles	≥ 10 000 cycles
2.7	Contact resistance	initial value	≤20 mΩ	≤20 mΩ
	Contact resistance	without electrical load	≤30 mΩ	≤30 mΩ
	after life expectancy	with electrical load	≤30 mΩ	≤30 mΩ
2.8	Insulation resistance		≥10 ¹¹ Ω	≥10 ¹¹ Ω
2.9	2.9 Capacity between 2 contacts		≤4 pF	≤4 pF
	Capacity between contact and ground		≤4 pF	≤4 pF

3.0 Mechanical Data	
3.1 Switching mode	Shorting or non-shorting
3.2 Stops	Fixed or without stop
3.3 Operating torque acc. to design	3 to 15 Ncm, MIL-version 10 to 20 Ncm
3.4 Stop strength	≥ 100 Ncm standard
	≥170 Ncm MIL-version
3.5 Fastening torque max.	70 Ncm standard
	150 Ncm MIL-version
3.6 Vibratory strength	10 g, 11 ms
3.7 Shock strength	50 g, 11 ms
3.8 Dust protection	Sealed wafer
3.9 Waterproofing	MIL-version watertight against front panel up to 0,2 bar

4.0 Other Data						
4.1 Contact material		Ag; special version Au over Ni barrier layer				
4.2 Insulating material	Wafer	Diallylphthalate, DAP; Code DI				
	Rotor	Polyacetal, POM				
4.3 Soldering time and temperature max.		5s at 260°C				
		3s at 350°C, manual soldering				



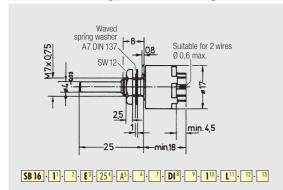
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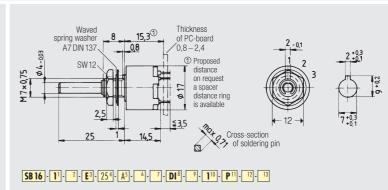
The bold-typed data in the yellow order blocks remain unchanged.

Normal-typed data match the drawings and can be modified according to your wishes.

Blanks need to be completed according to the ordering details on the inside front cover.

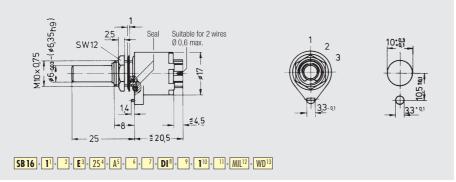
$\textbf{Dimensional Drawings and Contact Arrangements} \cdot \textit{Dimensions in mm}$

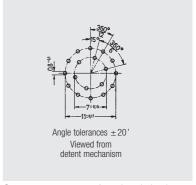




SB 16 · Standard version with soldering lugs

SB 16 Standard version with soldering pins



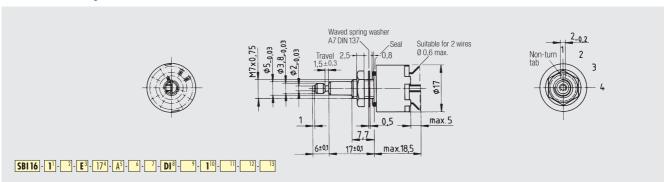


SB16 · MIL-version, shaft design A

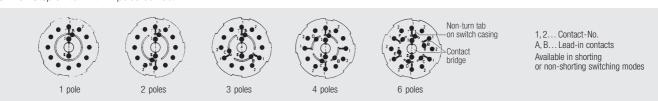
Contact arrangement for printed circuits



 $\ensuremath{\mathsf{SB16}}\xspace\cdot\ensuremath{\mathsf{Contact}}\xspace$ arrangements as viewed from detent mechanism



SBI16 · Step switch with impulse contact



SBI16 · Contact arrangements as viewed from detent mechanism